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5 🛛 V_{CC}

DBV OR DCK PACKAGE (TOP VIEW)

NC - No internal connection

NC

GND

A 🛛 2

3

- Operating Range of 4.5 V to 5.5 V
- Max t_{pd} of 7.5 ns at 5 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17

description/ordering information

The SN74AHCT1G04 contains one gate. The device performs the Boolean function $Y = \overline{A}$.

TA	PACKAGE	<u></u> ≢†	ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]							
	SOT (SOT-23) – DBV	Reel of 3000	SN74AHCT1G04DBVR	B04							
1000 40 0500	301 (301-23) - DBV	Reel of 250	SN74AHCT1G04DBVT	B04_							
–40°C to 85°C	SOT (SC-70) – DCK	Reel of 3000	SN74AHCT1G04DCKR	DC.							
	301 (30-70) - DCK	Reel of 250	SN74AHCT1G04DCKT	BC_							

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]The actual top-side marking has one additional character that designates the assembly/test site.

INPUT A	OUTPUT Y
Н	L
L	Н

FUNCTION TABLE

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
IOL	Low-level output current		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V
Τ _Α	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T _A = 25°C			MIN	МАХ	UNIT
FARAIVIETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	WIIIN	IVIAA	UNIT
Vau	I _{OH} = -50 μA					4.4		V
∨он	I _{OH} = -8 mA	4.5 V				3.8		v
Ve	$I_{OL} = 50 \mu A$				0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44	v
lj	$V_I = 5.5 V \text{ or GND}$	0 V to 5.5 V			±0.1		±1	μA
ICC	$V_I = V_{CC} \text{ or } GND, I_O = 0$	5.5 V			1		10	μA
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		4	10		10	pF

[‡]This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

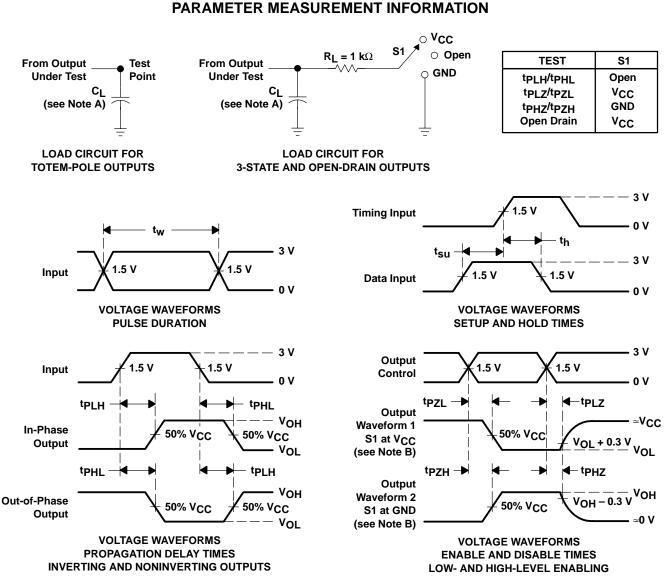
PARAMETER	FROM	то	LOAD	Т	T _A = 25°C			мах	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	WIAA	
^t PLH	٨	V	C 15 pE		4.7	6.7	1	7.5	20
^t PHL	А	Y C _L = 15 pF		4.7	6.7	1	7.5	ns	
^t PLH	٨	V	$C_{1} = 50 \text{ pF}$		5.5	7.7	1	8.5	20
^t PHL	А	Ŷ	Y $C_L = 50 pF$		5.5	7.7	1	8.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	14	pF



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



TEXAS INSTRUMENTS

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AHCT1G04DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT1G04DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G04DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G04DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G04DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT1G04DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74AHCT1G04 :

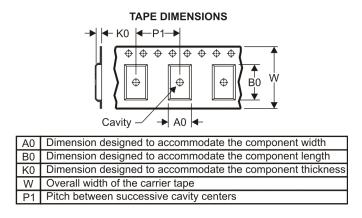
• Automotive: SN74AHCT1G04-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G04DBVT	SOT-23	DBV	5	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G04DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G04DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHCT1G04DCKT	SC70	DCK	5	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHCT1G04DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3



PACKAGE MATERIALS INFORMATION

22-Nov-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	565.0	140.0	75.0
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	205.0	200.0	33.0
SN74AHCT1G04DBVT	SOT-23	DBV	5	250	205.0	200.0	33.0
SN74AHCT1G04DCKR	SC70	DCK	5	3000	565.0	140.0	75.0
SN74AHCT1G04DCKR	SC70	DCK	5	3000	205.0	200.0	33.0
SN74AHCT1G04DCKT	SC70	DCK	5	250	205.0	200.0	33.0
SN74AHCT1G04DCKT	SC70	DCK	5	250	565.0	140.0	75.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.



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